

CMS25N10D-HF

N-Channel
RoHS Device
Halogen Free



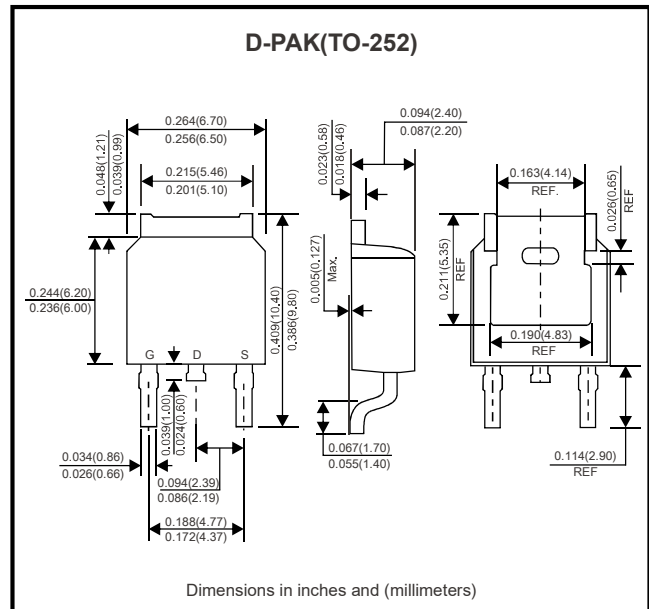
Features

- High Switching Speed
- Low Gate Charge
- Green Device Available
- Low Reverse Transfer Capacitance
- Improved dv/dt Capability
- 100% EAS Guaranteed

Description

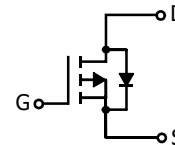
The CMS25N10D is the highest performance N-ch MOSFETs with super high dense cell design for extremely low $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The CMS25N10D meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.



Circuit diagram

- G : Gate
- D : Drain
- S : Source



Maximum Ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D @ T_C=25^\circ\text{C}$	25	A
	$I_D @ T_C=100^\circ\text{C}$	15	A
Pulsed Drain Current ^{1,2}	$I_{DM} @ T_C=25^\circ\text{C}$	100	A
Continuous Drain Current	$I_D @ T_A=25^\circ\text{C}$	4.4	A
	$I_D @ T_A=70^\circ\text{C}$	3.5	A
Total Power Dissipation ⁴	$P_D @ T_C=25^\circ\text{C}$	60	W
	$P_D @ T_A=25^\circ\text{C}$	2	W
Single Pulse Avalanche Energy, $L=0.1\text{mH}^3$	E_{AS}	26.4	mJ
Single Pulse Avalanche Current, $L=0.1\text{mH}^3$	I_{AS}	23	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

Thermal Data

Parameter	Symbol	Conditions	Max. Value	Unit
Thermal Resistance Junction-ambient ¹	$R_{\theta JA}$	Steady State	62.5	$^\circ\text{C/W}$
Thermal Resistance Junction-case ¹	$R_{\theta JC}$	Steady State	2.0	$^\circ\text{C/W}$

Company reserves the right to improve product design , functions and reliability without notice.

Electrical Characteristics (at $T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	100	-	-	V	$V_{GS}=0, I_D=250\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	1.0	1.7	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS}= \pm 20\text{V}$
Drain-Source Leakage Current($T_J=25^{\circ}\text{C}$)	I_{DSS}	-	-	1	μA	$V_{DS}=80\text{V}, V_{GS}=0$
Drain-Source Leakage Current($T_J=55^{\circ}\text{C}$)		-	-	100		$V_{DS}=80\text{V}, V_{GS}=0$
Static Drain-Source On-Resistance ²	$R_{DS(ON)}$	-	-	48	m Ω	$V_{GS}=10\text{V}, I_D=25\text{A}$
		-	-	50		$V_{GS}=4.5\text{V}, I_D=15\text{A}$
Total Gate Charge ²	Q_g	-	60	-	nC	$I_D=20\text{A}$ $V_{DS}=80\text{V}$ $V_{GS}=10\text{V}$
Gate-Source Charge	Q_{gs}	-	9.7	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	11.8	-		
Turn-on Delay Time ²	$T_{d(on)}$	-	10.4	-	ns	$V_{DD}=50\text{V}$ $I_D=20\text{A}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$
Rise Time	T_r	-	46	-		
Turn-off Delay Time	$T_{d(off)}$	-	54	-		
Fall Time	T_f	-	10	-		
Input Capacitance	C_{iss}	-	3848	-	pF	$V_{GS}=0\text{V}$ $V_{DS}=15\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	C_{oss}	-	137	-		
Reverse Transfer Capacitance	C_{rss}	-	82	-		
Gate Resistance	R_g	-	1.6	3.2	Ω	$f=1.0\text{MHz}$

Guaranteed Avalanche Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Single Pulse Avalanche Energy ⁵	EAS	5	-	-	mJ	$V_{DD}=25\text{V}, L=0.1\text{mH}, I_{AS}=10\text{A}$

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage ²	V_{SD}	-	0.7	1.0	V	$I_S=1\text{A}, V_{GS}=0\text{V}, T_J=25^{\circ}\text{C}$
Continuous Source Current ^{1,6}	I_S	-	-	25	A	---

Notes: 1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.

2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

3. The EAS data shows Max. rating. The test condition is $V_{DD}=25\text{V}, V_{GS}=10\text{V}, L=0.1\text{mH}, I_{AS}=23\text{A}$.

4. The power dissipation is limited by 150°C junction temperature.

5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

RATING AND CHARACTERISTIC CURVES

Typical Characteristics

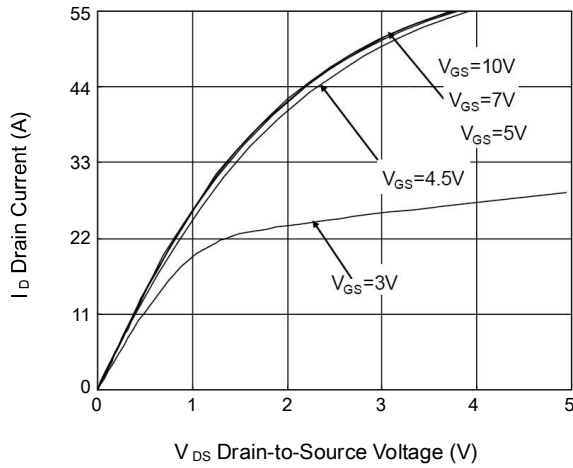


Fig.1 Typical Output Characteristics

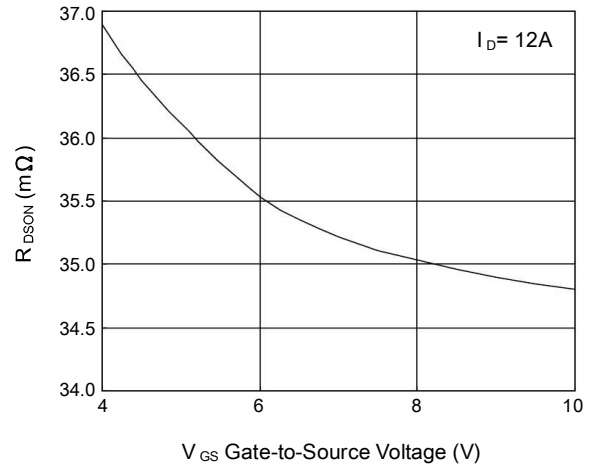


Fig.2 On-Resistance vs. G-S Voltage

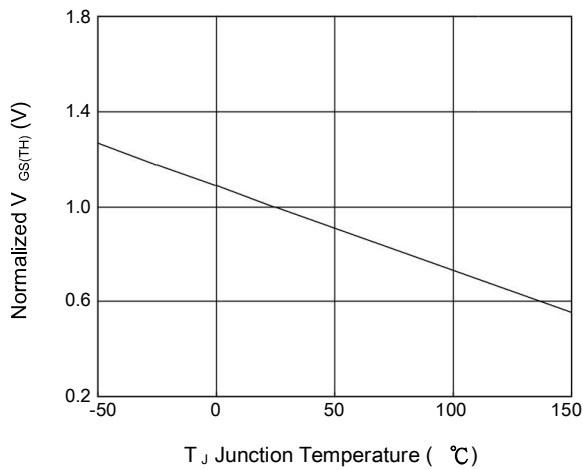


Fig.3 Normalized $V_{GS(th)}$ vs. T_J

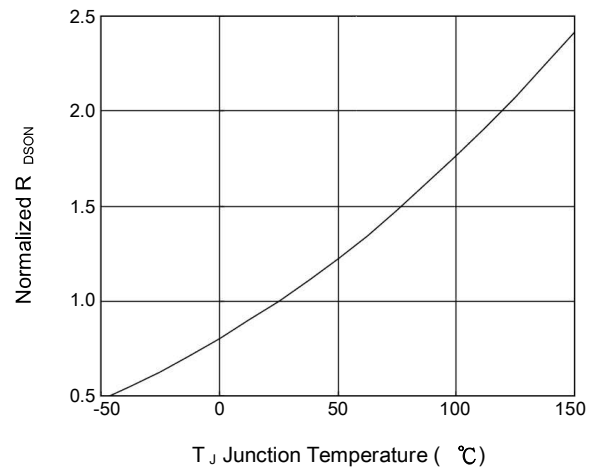


Fig.4 Normalized $R_{DS(on)}$ vs. T_J

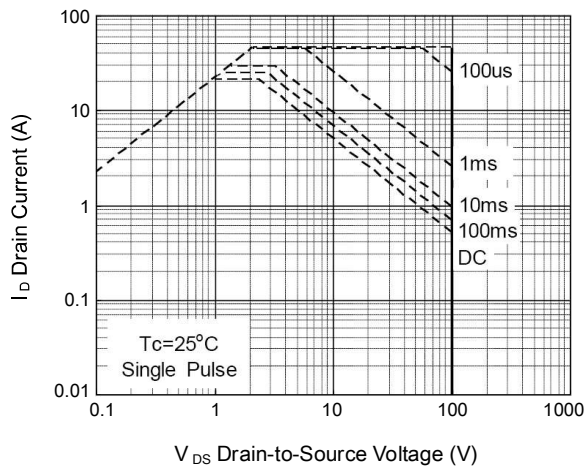


Fig.5 Safe Operating Area

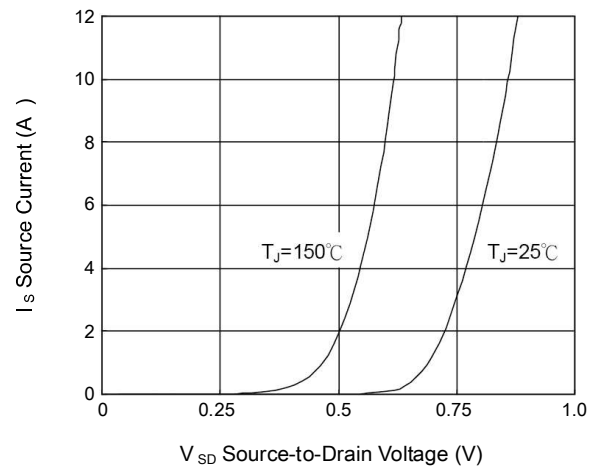


Fig.6 Forward Characteristics of Reverse

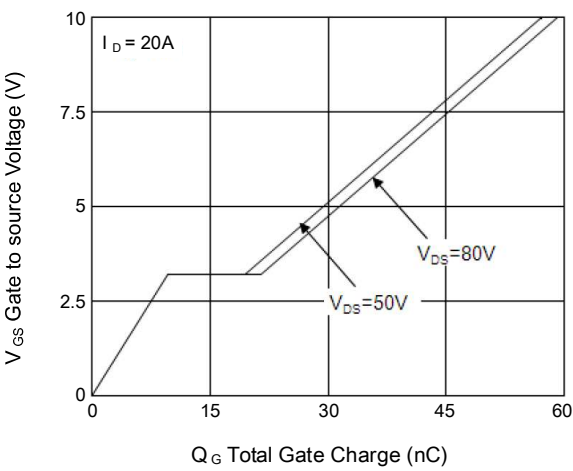


Fig.7 Gate Charge Characteristics

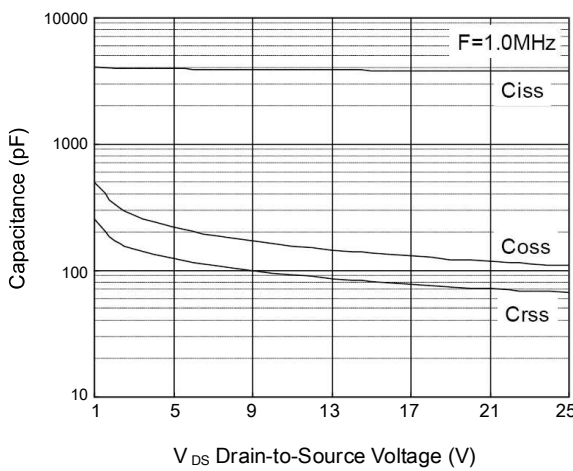


Fig.8 Capacitance Characteristics

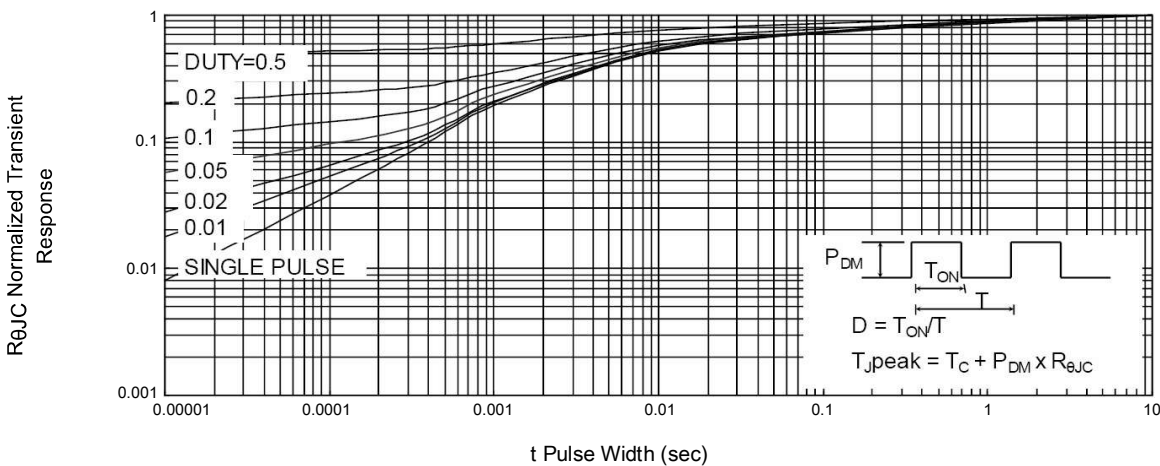


Fig.9 Normalized Maximum Transient Thermal Impedance

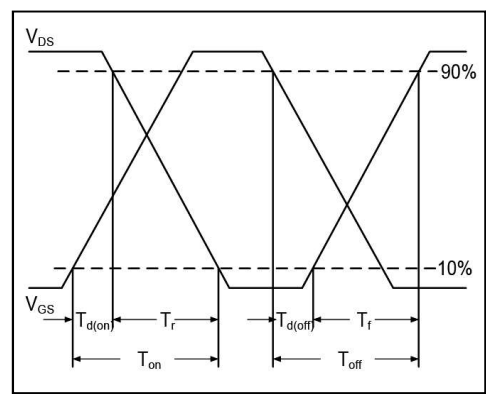


Fig.10 Switching Time Waveform

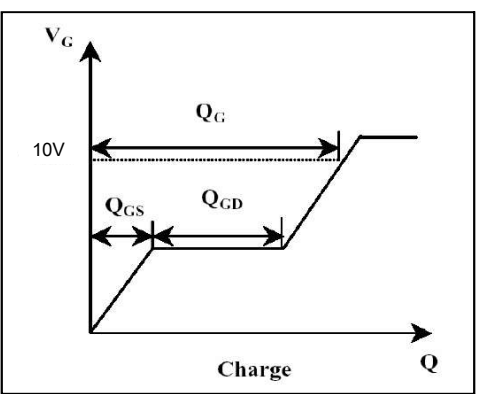
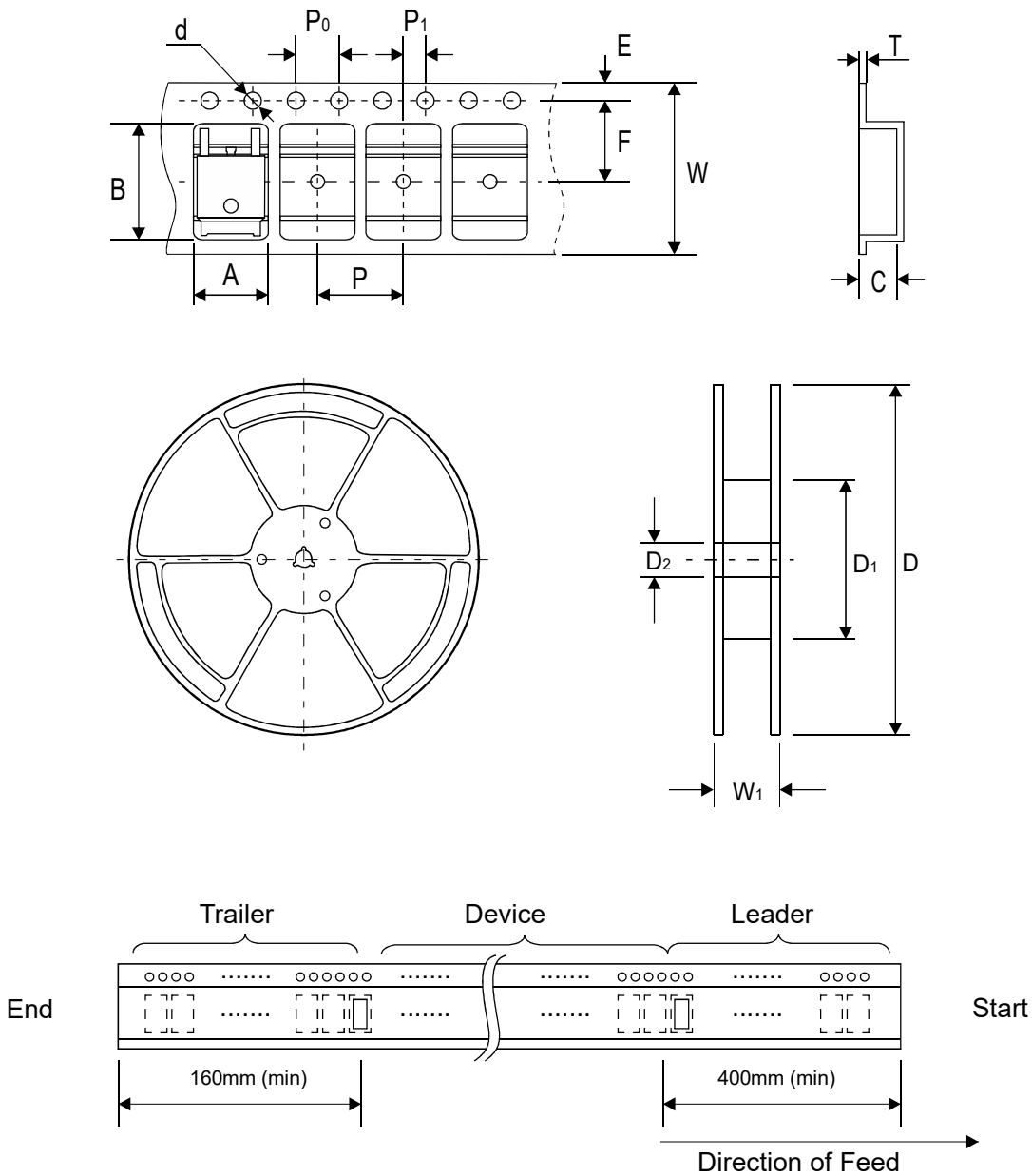


Fig.11 Gate Charge Waveform

Reel Taping Specification

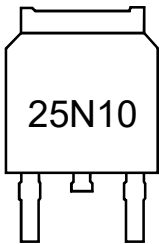


TO-252 (D-PAK)	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	6.90 ± 0.10	10.50 ± 0.10	2.70 ± 0.10	1.55 ± 0.05	330.00 ± 2.00	100.00 ± 1.00	13.00 ± 1.00
	(inch)	0.272 ± 0.004	0.413 ± 0.004	0.106 ± 0.004	0.061 ± 0.002	12.992 ± 0.079	3.937 ± 0.039	0.512 ± 0.039

TO-252 (D-PAK)	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	7.50 ± 0.10	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	0.30 ± 0.05	16.00 ± 0.10	21.00 ± 1.00
	(inch)	0.069 ± 0.004	0.295 ± 0.004	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	0.012 ± 0.002	0.630 ± 0.004	0.827 ± 0.039

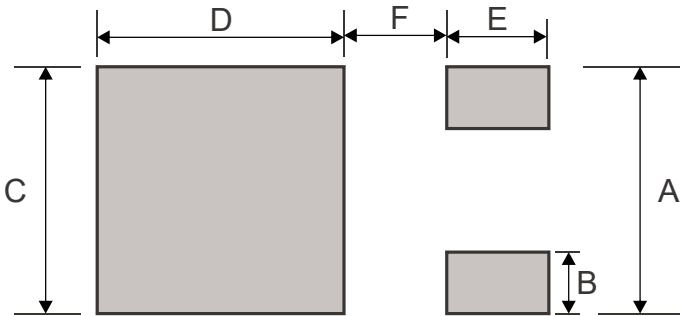
Marking Code

Part Number	Marking Code
CMS25N10D-HF	25N10



Suggested PAD Layout

SIZE	TO-252 / DPAK	
	(mm)	(inch)
A	6.17	0.243
B	1.60	0.063
C	5.80	0.228
D	6.20	0.244
E	3.00	0.118
F	2.58	0.101



Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	REEL SIZE (inch)
TO-252/D-PAK	2,500	13